



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSZ067N06LS3 G	Issued	10. May 2021
MA#	MA001605018		
Package	PG-TSDSON-8-2	Weight*	38.75 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.817	4.69	4.69	46907	46907
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		54	
	non noble metal	zinc	7440-66-6	0.008	0.02		216	
	non noble metal	iron	7439-89-6	0.168	0.43		4327	
	non noble metal	copper	7440-50-8	6.808	17.57	18.03	175706	180303
wire	non noble metal	copper	7440-50-8	0.036	0.09	0.09	935	935
encapsulation	organic material	carbon black	1333-86-4	0.034	0.09		870	
	plastics	epoxy resin	-	1.735	4.48		44786	
	inorganic material	silicondioxide	60676-86-0	15.078	38.93	43.50	389160	434816
leadfinish	non noble metal	tin	7440-31-5	0.387	1.00	1.00	9992	9992
plating	noble metal	silver	7440-22-4	0.963	2.48	2.48	24844	24844
solder	non noble metal	tin	7440-31-5	0.037	0.09		944	
	noble metal	silver	7440-22-4	0.046	0.12		1180	
	non noble metal	lead	7439-92-1	1.746	4.51	4.72	45067	47191
heat sink clip	inorganic material	phosphorus	7723-14-0	0.002			49	
	non noble metal	zinc	7440-66-6	0.008	0.02		195	
	non noble metal	iron	7439-89-6	0.151	0.39		3895	
	non noble metal	copper	7440-50-8	6.127	15.81	16.22	158143	162282
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			28	
	non noble metal	zinc	7440-66-6	0.004	0.01		111	
	non noble metal	iron	7439-89-6	0.086	0.22		2226	
	non noble metal	copper	7440-50-8	3.501	9.04	9.27	90365	92730
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com